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(54) Title: ACOUSTIC TRANSDUCER AND METHOD OF FORMING THE SAME

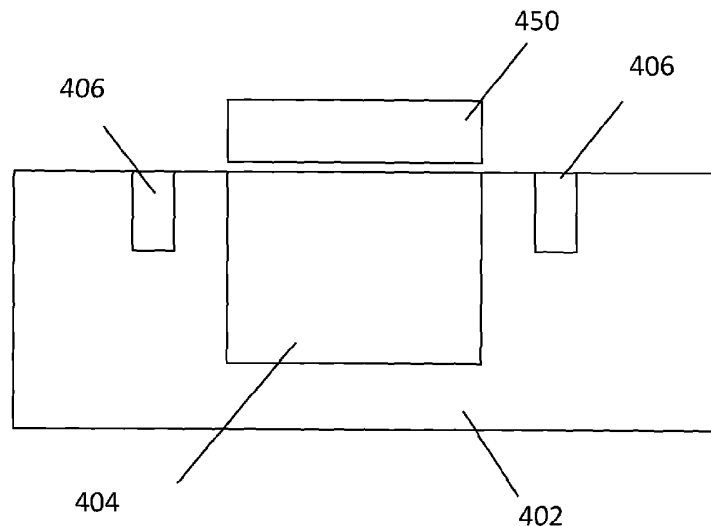


FIG. 4

(57) Abstract: Various embodiments may relate to an acoustic transducer. The acoustic transducer may include a substrate including a cavity extending from a surface of the substrate, wherein the substrate further includes one or more acoustic channels, each of the one or more acoustic channels having a depth extending from the surface of the substrate and a length, the length greater than the depth, extending at least partially around the cavity. The acoustic transducer may also include a layered arrangement suspended over the cavity. The one or more acoustic channels may be configured to include an acoustic medium having a specific acoustic impedance lower than a specific acoustic impedance of the substrate.

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